



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



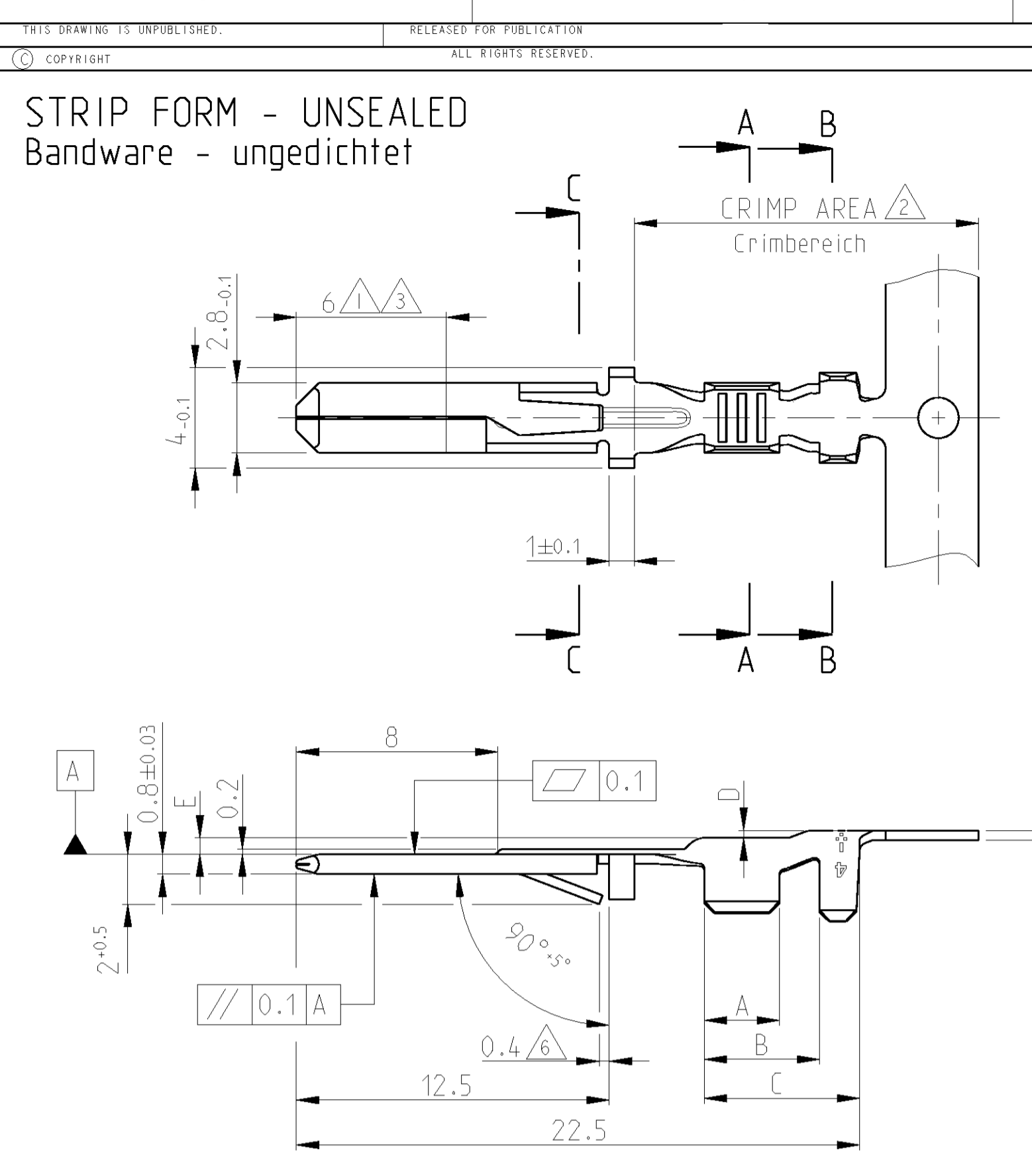
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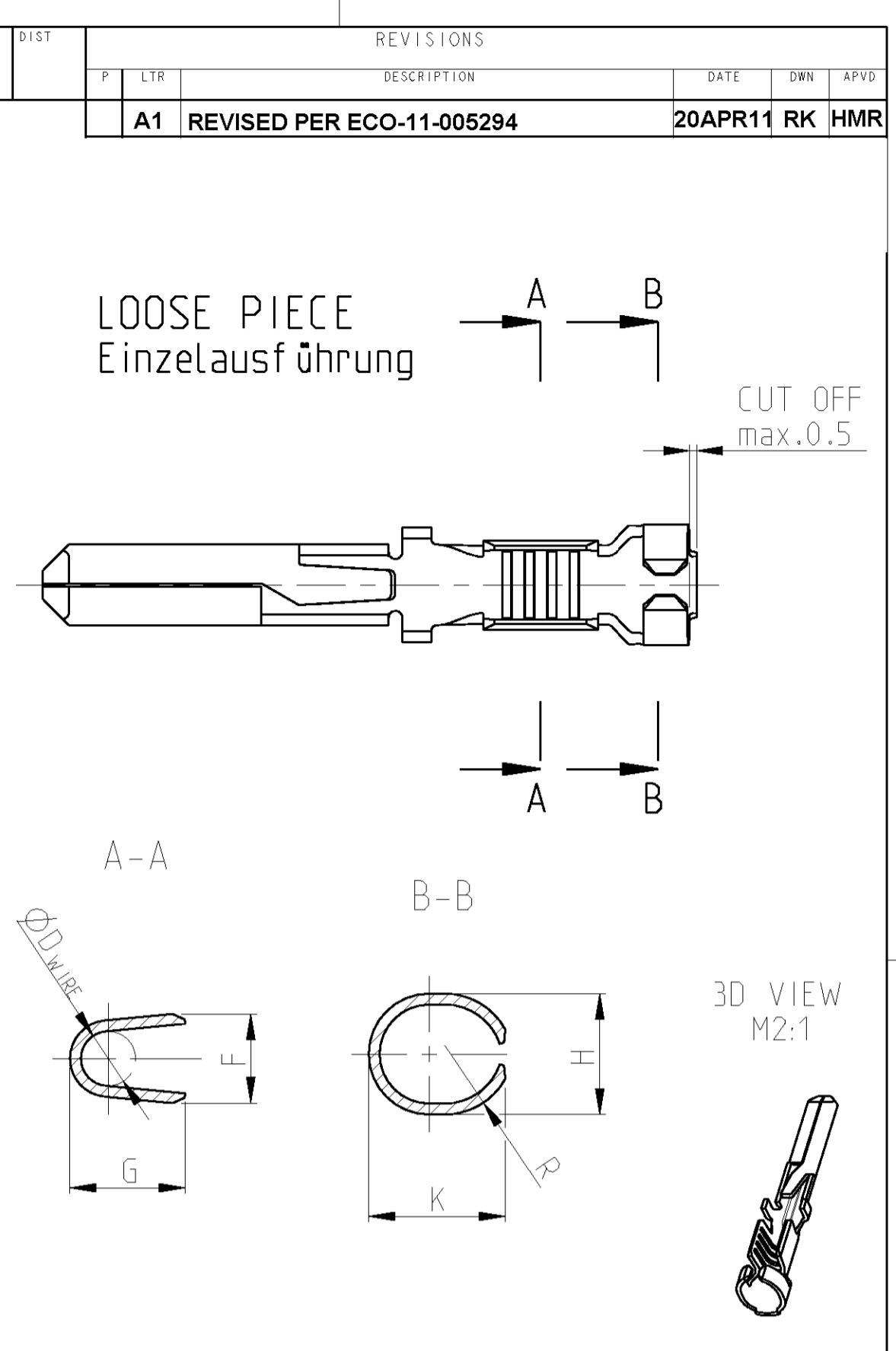
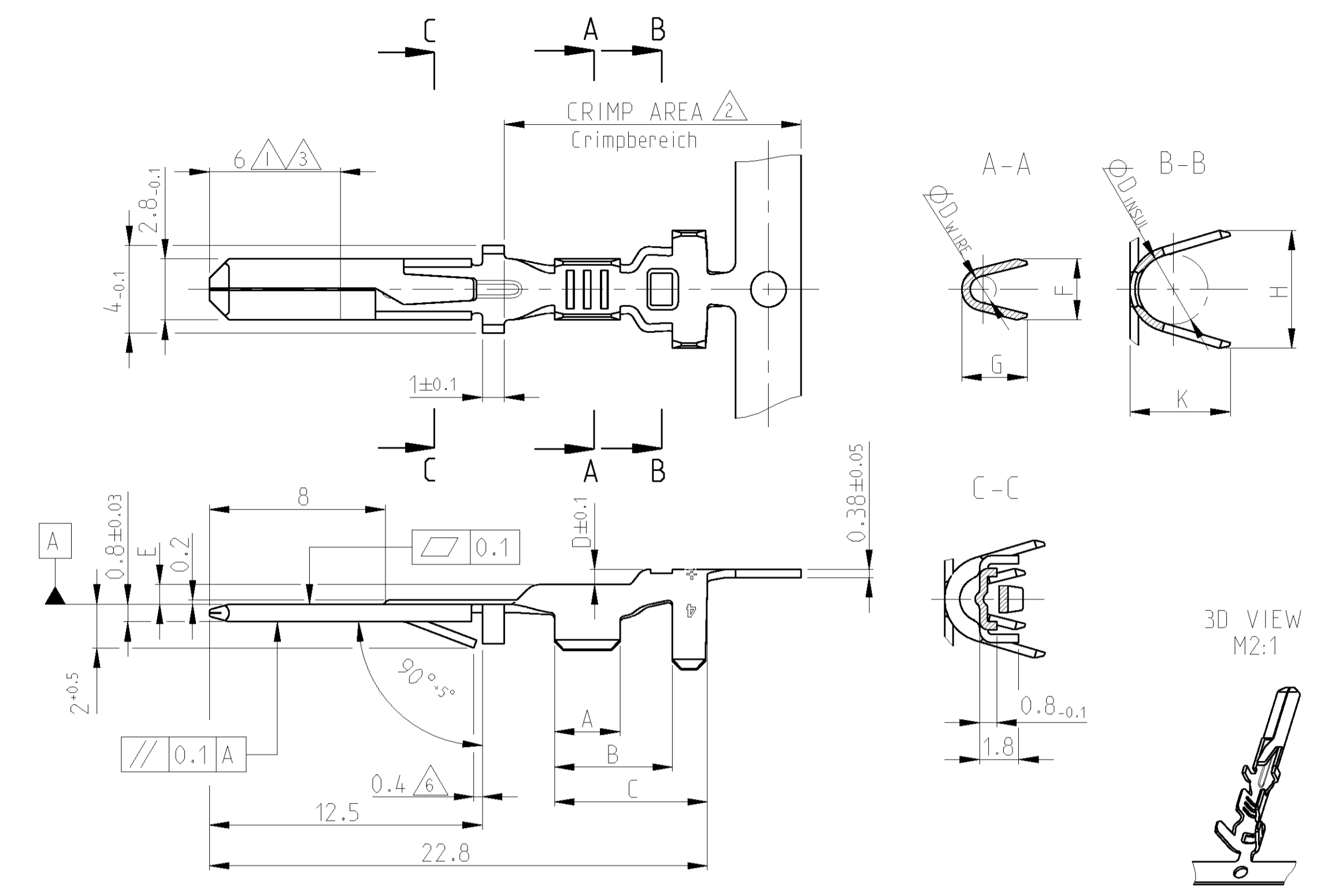
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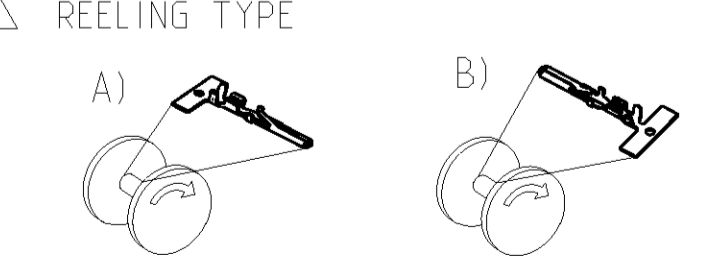
STRIP FORM - SINGLE WIRE SEAL
Bandware - Einzel-Dichtung System



HAND TOOL Handzage	APPLICATOR Anschlag-WKZ	INSULATION BARREL Isolationsbereich					WIRE BARREL Drahtbereich					INSULATION BARREL Isolationsbereich					WIRE BARREL Drahtbereich					E	D	C	B	A	REELING	INSULATION RANGE Isolations- durchmesser	WIRE RANGE DGB [mm 2]	FINISH Oberfläche	MATERIAL	TE CONNECTIVITY ORDER No. LOOSE PIECE Einzelauflührung	REV	TE CONNECTIVITY ORDER No. STRIP FORM Bandware	
		K	H	R	G	F	D _{WIRE}	K	H	R	G	F	D _{WIRE}	K	H	R	G	F	D _{WIRE}	K	H														R
N/A	N/A	4.3	4.8	2.8	4.0	3.1	1.7	4.6	5.6	3.6	4.0	3.8	1.7	0.85	0.95	7.5	5.9	3.5	∅3.4	1.0 - 2.5 FLR	PRETINNED min.1µm	CuSn4	0-965975-5	J	0-929949-5	SEL. GOLD PLATED	CuZn30	0-965975-4	J	0-929949-4	PLAIN	CuZn30	0-965975-3	J	0-929949-3
N/A	N/A	4.3	4.8	2.8	3.0	2.2	1.2	4.6	5.4	3.2	3.0	2.8	1.2	0.9	0.7	7.0	5.4	3.0	∅3.4	0.5 - 1.0 FLR	PRETINNED min.1µm	CuSn4	0-965974-7	A	0-929948-7	SEL. GOLD PLATED	CuSn4	0-965974-6	A	0-929948-6	PLAIN	CuZn30	0-965974-5	J	0-929948-5
2-1579001-1 WITH DIE SET: mit Matrize: 1579001-2	N/A	2.5	2.5	1.4	2.2	2.0	0.8	2.8	2.8	1.4	2.2	2.2	0.8	0.65	0.2	5.7	4.1	2.5	∅1.15 - 1.6	0.2 - 0.5 FLR	PRETINNED min.1µm	CuSn4	0-963962-5	D	0-963961-5	SEL. GOLD PLATED	CuZn30	0-963962-4	D	0-963961-4	PLAIN	CuZn30	0-963962-3	D	0-963961-3
539635-1 WITH DIE SET: mit Matrize: 539743-2	878416-0	3.7	3.1	1.8	3.0	2.2	1.2	4.1	3.9	1.8	3.0	2.8	1.2	0.65	0.2	6.2	4.6	3.0	∅1.4 - 2.3	0.5 - 1.0 FLR	PRETINNED min.1µm	CuSn4	0-963962-2	D	0-963961-2	SEL. SILVER PLATED	CuZn30	0-963962-1	D	0-963961-1	PLAIN	CuZn30	0-963962-0	D	0-963961-0
169400 WITH DIE SET: mit Matrize: 734262 - 0	878402-0	4.4	3.8	2.3	4.0	3.1	1.8	4.9	4.7	2.6	4.0	3.8	1.8	1.15	0.3	7.2	5.6	4.0	∅1.8 - 2.9	1.0 - 2.5 FLR	PRETINNED min.1µm	CuSn4	0-928931-5	P	0-928930-5	SEL. GOLD PLATED	CuZn30	0-928931-4	P	0-928930-4	PLAIN	CuZn30	0-928931-3	P	0-928930-3
N/A	878227-0	4.8	4.2	2.4	4.0	3.1	1.9	5.3	4.8	3.1	4.0	3.8	1.9	1.15	0.4	7.2	5.6	4.0	∅2.3 - 3.5 RB-Leitung	1.5 - 3 FLR	PRETINNED min.1µm	CuSn4	0-928931-2	P	0-928930-2	SEL. SILVER PLATED	CuZn30	0-928931-1	P	0-928930-1	PLAIN	CuZn30	0-928931-0	P	0-928930-0
N/A	N/A	3.3	3.1	1.8	3.0	2.2	1.2	3.65	3.6	2.0	3.0	2.8	1.2	0.65	0.3	6.2	4.6	3.0	∅1.6 - 2.2 RB-Leitung	0.5 - 1.0 FLR	PRETINNED min.1µm	CuSn4	0-928794-5	R	0-928781-5	SEL. GOLD PLATED	CuZn30	0-928794-4	R	0-928781-4	PLAIN	CuZn30	0-928794-3	R	0-928781-3

NOTES:
Bemerkungen

- 1 CONTACT AREA min.0.75µm Au OVER min.1.25µm Ni
Kontaktbereich min.0.75µm Au über min.1.25µm Ni
- 2 CRIMP AREA 1-2µm Sn OVER min.0.05µm Ni
Crimpbereich 1-2µm Sn über min.0.05µm Ni
- 3 Min.3µm Ag IN LOCALIZED AREA. FLASH Ag ON REMAINDER.
BOTH OVER min.1.25µm Ni
Min.3µm Ag im lokalisierte Bereich. Rest flashversilbert. beide über min.1.25µm Ni
- 4 ALL VERSIONS SPLICE FREE EXCEPT OF
Alle Versionen Splice-free außer
- 5 SPLICE ACCORDING TO TE CONNECTIVITY-SPEC. 118-10107 SPLICE ADDITIONAL MARK
WITH RED SPLICE-STICKER ON THE INTERLEAVING PAPER AND ON THE REEL
Splice nach Tyco-Spec. 118-10107 zusätzlich Splice mit rotem Splice-Aufkleber
auf dem Zwischentagenpapier und auf dem Reel kennzeichnen
- 6 TO BE MEASURED BY DIMENSION 2 mm
Bei Ausstellung 2 mm
- 7 REELING TYPE



DIMENSIONS: mm	TOLERANCES UNLESS OTHERWISE SPECIFIED: ISO 2768 -H E	DRN P. Hasek	Z1AUG2006 60CT2006	TE Connectivity
MATERIAL see table siehe Tabelle	FINISH see table siehe Tabelle	APVD P. Vlcek	90CT2006	TE Connectivity
PRODUCT SPEC 108-18299		PRODUCT GROUP DRAWING FOR 2.8 mm FASTIN-FASTON® TAB		
APPLICATION SPEC 114-18014		SIZE A1 00779 C=1670467		
CUSTOMER DRAWING		SCALE 5:1 SHEET 1 OF 1 REV A1		